

THRU HOLE

SURFACE MOUNT

PERFORMANCE AND MATERIALS SPECIFICATIONS

Thermal Performance [FR-4 Standard]:

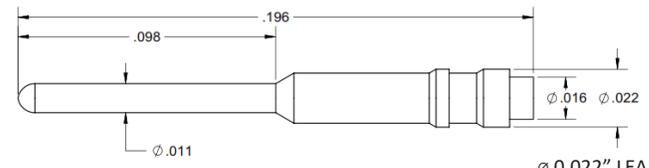
Operating Temperature Range:	-55° to 140°C
Glass Transition Temperature Range:	150° to 200°C
Resistance to Soldering Heat:	10 seconds @ 288°C
Flammability Rating [UL-94]:	UL94V-0
IEC Climatic Category:	55/125/21

Electrical Performance: Tests IAW MIL-STD-202 or 1344 Methods:

Maximum Voltage:	75 VAC / 100 VDC
Maximum Current:	1 Amperes per contact
Contact Resistance: Dry Circuit:	.01 Ω Max. @ .1 Amps/5 VDC
Insulation Resistance, @ 500 VDC	10,000 MΩ Min.
Dielectric Withstanding Voltage	500 VAC Min.
Capacitance:	1 pf [PicoFarads] Max.
Self Inductance	2 nH [NanoHenries] Max.

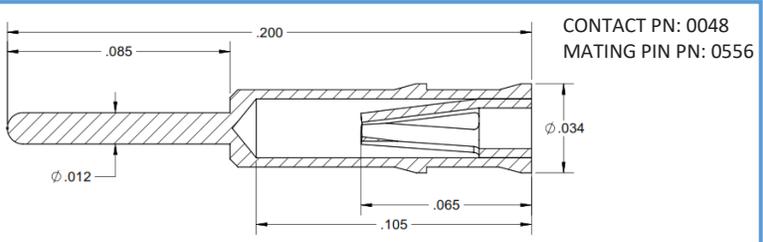
Contact Materials & Finishes [Other finishes available]:

Bodies:	Brass Alloy C36000 per ASTM-B16, ½ Hard Plated 10µIn. Min. Gold over 100µIn. Min. Nickel, [or] 100µIn. Min. Tin Over 100µIn. Min. Nickel
Contacts:	Beryllium Copper Alloy C17200 per ASTM-B194 Plated 10µIn. Min. Gold over 50µIn. Min. Nickel
Solder Balls:	Eutectic, Sn 96.5/Ag 3.0/Cu .5 Solder, Ø.015 ~ Ø.020 Melting Temperature 218.5° C [425.3°F]



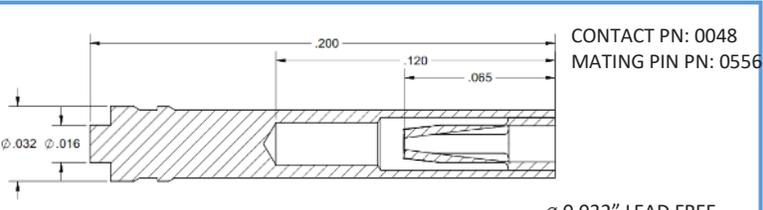
P/N 0556

Ø 0.022" LEAD FREE
SOLDER BALL
(USED FOR SERIES 900)



P/N 0104

CONTACT PN: 0048
MATING PIN PN: 0556



P/N 0799

Ø 0.032" LEAD FREE
SOLDER BALL

PART NUMBER: ORDERING INFORMATION

300 - **640** - **F** - **0556** - **11A4**
PRODUCT CODE PIN COUNT MATERIAL CONTACT P/N PATTERN CODE

300 = Socket Pin Grid Array [PGA]
900 = LGA Interposer [BPGA]
1000 = Socket, Ball Grid Array [SBGA]
1200 = Ball Grid Array Interposer [PBGA]

A = ACRYLIC
E = PEEK [POLYETHERETHERKETONE]
H = POLYIMIDE, [MIL-L-13949/10]
F = FR-4, [IPC 4101/24]
R = RYTON [POLYPHENYLENE SULFIDE]
U = G.E. ULTEM [POLYETHERIMIDE]

OVER 25,000 PATTERNS
AVAILABLE

If unknown put XXXX
Factory will add pattern
code

